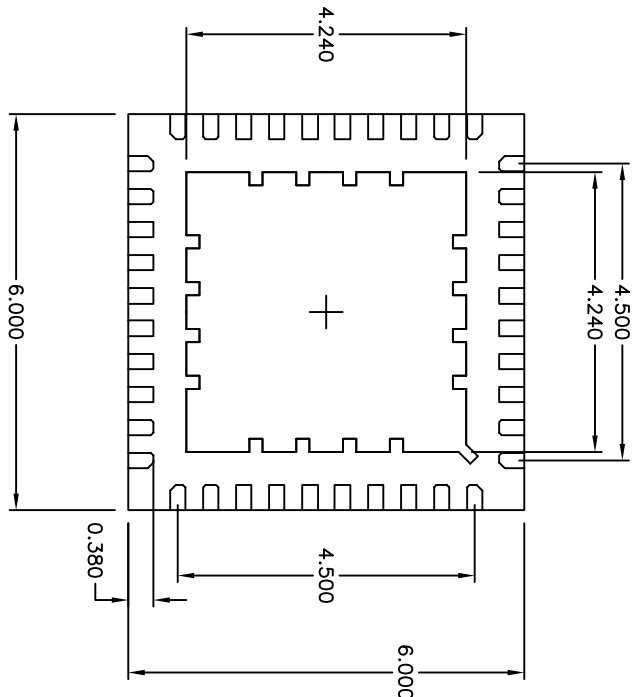
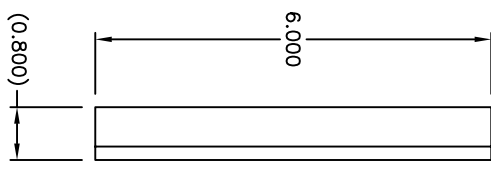
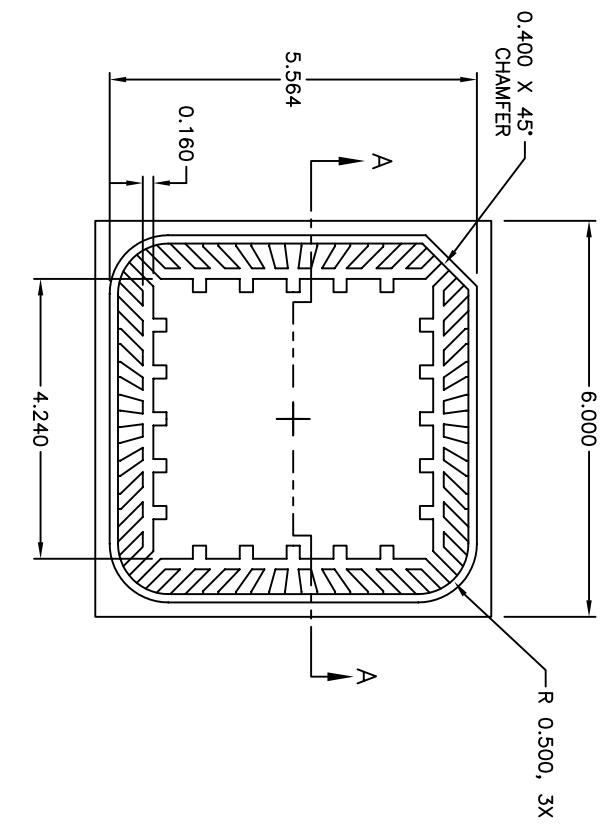


2

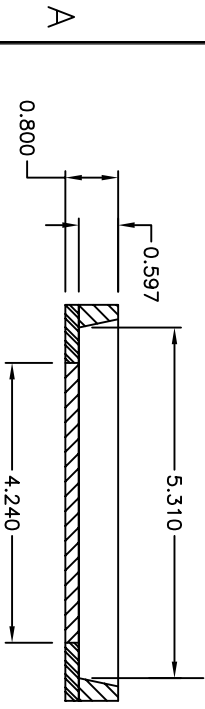
1

REVISIONS			APPROVED
EON NO.	DATE	DESCRIPTION	D.BENAVANDO
10627	3/20/06	PRODUCTION RELEASE	



TOP VIEW

BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 3. LEAD FRAME: COPPER, 194 FH.
 4. LEAD FINISH: FULL GOLD PLATE.
 5. FRAME THICKNESS: 0.2030 ±.0076.
 6. DIE PAD: 4.240mm X 4.240mm.
 7. JEDEC OUTLINE: MO-220 (VJUD-5).

	THIRD ANGLE PROJECTION
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS	
XXX ± 0.015	XXXX ± ---
XXXX ± 0.050	ANGLES: ± 1°
DO NOT SCALE DRAWING	

DRAWN BY	GRIFFITTS	DATE	3/19/06
APP BY	P. FLASKERUD	DATE	3/20/06
CUSTOMER	---		
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40 Lead 6mm x 6mm
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP6X6-40-OP-01	1
SCALE	NONE	FILE
	MLP6X6-40-OP-01-R1.DWG	SHEET 1 OF 1

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